

### **Description**

The AP180N03D uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

#### **General Features**

V<sub>DS</sub>=30V I<sub>D</sub> =180A

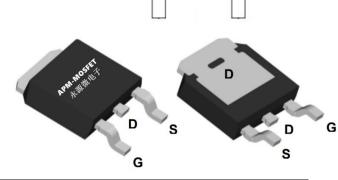
 $R_{DS(ON)} < 3.2 \text{m}\Omega$  @  $V_{GS}$ =10V (Type: 2.1m $\Omega$ )

#### **Application**

Battery protection

Load switch

Uninterruptible power supply



### **Package Marking and Ordering Information**

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Product ID	Pack	Marking	Qty(PCS)	
AP180N03D	TO-252-3L	AP180N03D XXXX YYYY	2500	

## Absolute Maximum Ratings (T<sub>C</sub>=25°Cunless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	30	V
Vgs	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1,6</sup>	180	А
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1,6</sup>	145	А
Ідм	Pulsed Drain Current <sup>2</sup>	500	Α
EAS	Single Pulse Avalanche Energy <sup>3</sup>	246	mJ
las	Avalanche Current	70.2	Α
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	187	W
Тѕтс	Storage Temperature Range	-55 to 175	°C
TJ	Operating Junction Temperature Range	-55 to 175	°C
Reja	Thermal Resistance Junction-Ambient <sup>1</sup>	62	°C/W
Rejc	Thermal Resistance Junction-Case <sup>1</sup> 0.8		°C/W

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## Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BVDSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	30	38		V	
∆BVDSS/∆TJ	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =1mA		0.014		V/°C	
RDS(ON)	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =30A		2.1	3.2	mΩ	
TOO(ON)	Static Brain-Gource On-Resistance	V <sub>GS</sub> =4.5V , I <sub>D</sub> =15A		3.0	3.8	11122	
VGS(th)	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1.2	1.6	2.5	V	
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	VGS-VDS, ID -230UA		-4		mV/°C	
IDSS	Drain Source Leakage Current	V <sub>DS</sub> =24V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C			1		
1033	Drain-Source Leakage Current	V <sub>DS</sub> =24V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C			5	uA	
IGSS	Gate-Source Leakage Current	$V_{GS}$ =±20 $V$ , $V_{DS}$ =0 $V$	-		±100	nA	
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =30A		50		S	
$R_g$	Gate Resistance	$V_{DS}$ =0V , $V_{GS}$ =0V , f=1MHz		1.7		Ω	
Qg	Total Gate Charge (4.5V)			56.9			
Qgs	Gate-Source Charge	V <sub>DS</sub> =15V , V <sub>GS</sub> =10V , I <sub>D</sub> =15A		13.8		nC	
Qgd	Gate-Drain Charge			23.5			
Td(on)	Turn-On Delay Time		-	20.1			
Tr	Rise Time	$V_{DD}$ =15V , $V_{GS}$ =10V $R_{G}$ =3.3 $\Omega$ ,		6.3		no	
Td(off)	Turn-Off Delay Time	I <sub>D</sub> =1A	-	124.6		ns	
T <sub>f</sub>	Fall Time			15.8			
Ciss	Input Capacitance			5850			
Coss	Output Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		720		pF	
Crss	Reverse Transfer Capacitance			525			
IS	Continuous Source Current <sup>1,5</sup>	\/\/0\/			205	Α	
ISM	Pulsed Source Current <sup>2,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	-		500	Α	
VSD	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =1A , T <sub>J</sub> =25°C			1.2	V	

#### Note:

- 1. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.
- $2_{\times}$  The data tested by pulsed , pulse width  $\leqq 300 us$  , duty cycle  $\leqq 2\%$
- 3. The EAS data shows Max. rating . The test condition is VDD=25V,VGS=10V,L=0.1Mh,IAS=22A
- 4. The power dissipation is limited by 175°C junction temperature
- 5. The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation.



## **Typical Characteristics**

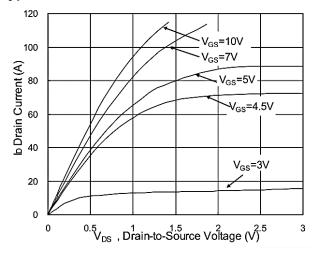


Fig.1 Typical Output Characteristics

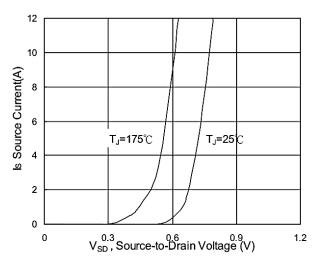


Fig.3 Forward Characteristics of Reverse

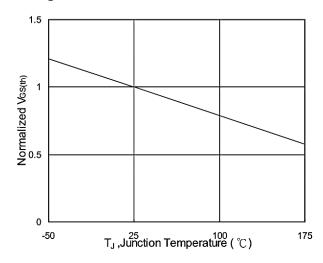


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$ 

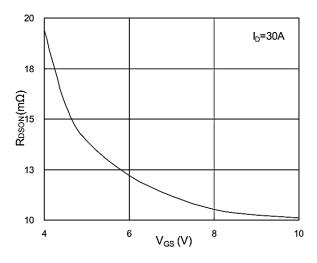


Fig.2 On-Resistance vs. G-S Voltage

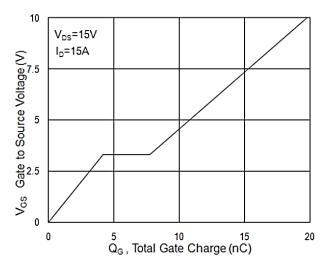


Fig.4 Gate-Charge Characteristics

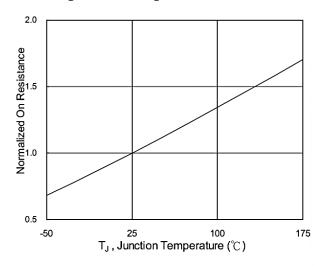
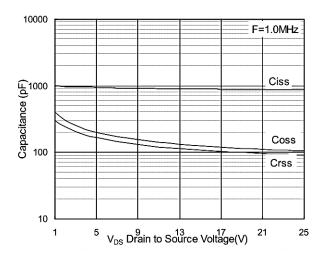


Fig.6 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>







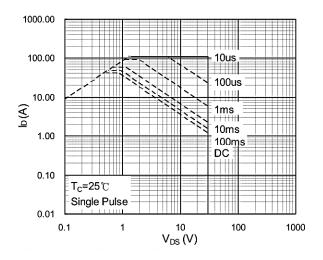


Fig.7 Capacitance

Fig.8 Safe Operating Area

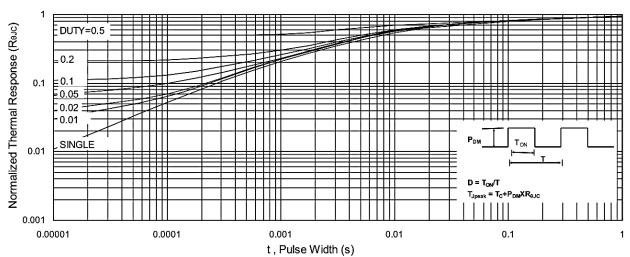


Fig.9 Normalized Maximum Transient Thermal Impedance

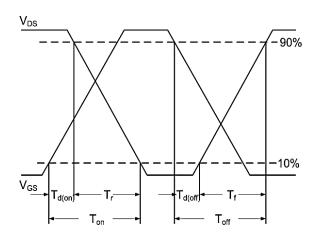


Fig.10 Switching Time Waveform

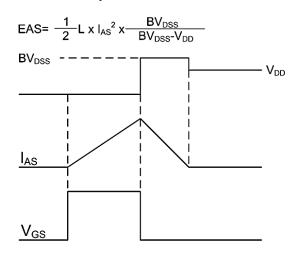
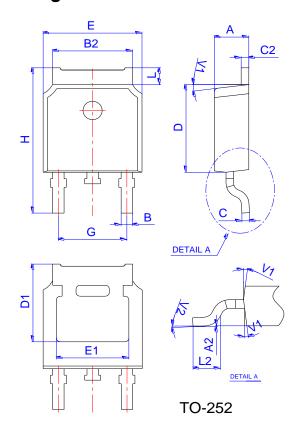


Fig.11 Unclamped Inductive Switching Waveform

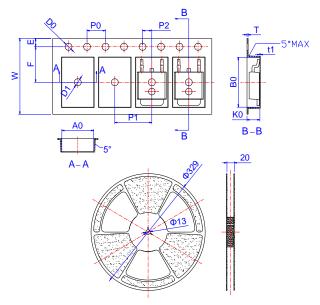


# Package Mechanical Data:TO-252-3L



	Dimensions					
Ref.		Millimeters		Inches		
	Min.	Тур.	Max.	Min.	Тур.	Max.
Α	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
В	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
С	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF		0.209REF			
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
Н	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

# **Reel Spectification-TO-252**



	Dimensions					
Ref.	Millimeters			Inches		
	Min.	Тур.	Max.	Min.	Тур.	Max.
W	15.90	16.00	16.10	0.626	0.630	0.634
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
D0	1.40	1.50	1.60	0.055	0.059	0.063
D1	1.40	1.50	1.60	0.055	0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
A0	6.85	6.90	7.00	0.270	0.271	0.276
В0	10.45	10.50	10.60	0.411	0.413	0.417
K0	2.68	2.78	2.88	0.105	0.109	0.113
Т	0.24		0.27	0.009		0.011
t1	0.10			0.004		
10P0	39.80	40.00	40.20	1.567	1.575	1.583



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Edition	Date	Change
Rve1.0	2020/5/1	Initial release

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